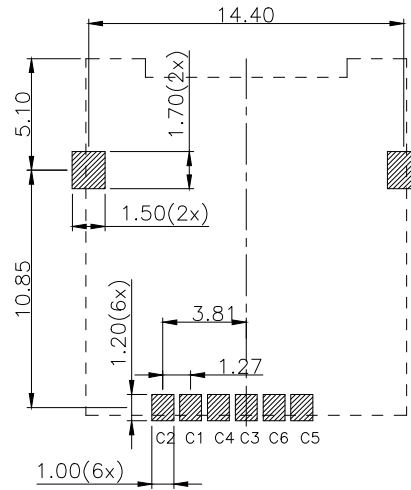
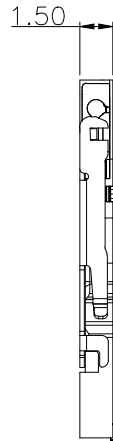
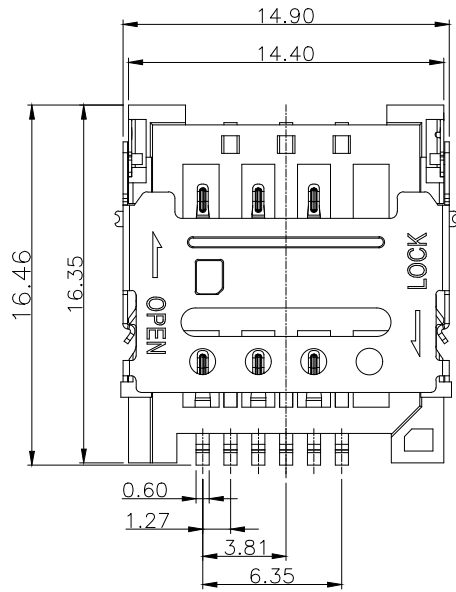
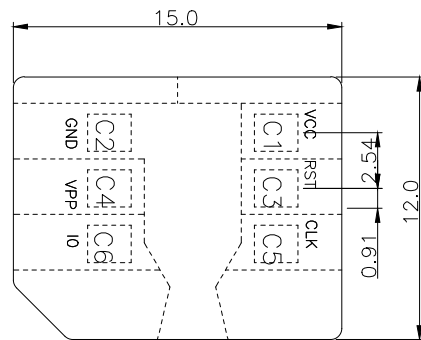
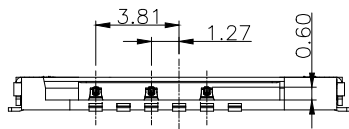
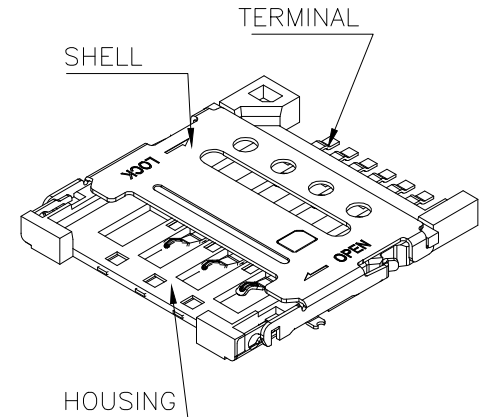


Customer drawings  
Reference only

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2017/10/17



RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES:±0.05



MICRO SIM

NOTES:

- MATERIALS
  - HOUSING : LCP S475
  - TERMINAL: C5210
  - SHELL : SUS 201
- FINISH
  - TERMINAL:GOLD PLATED 1u" ON CONTACT AREA, G/F GOLD PLATED ON SOLDER TAILS.
  - PEG: G/F GOLD PLATED ON SOLDER TAILS.
- MECHANICAL CHARACTERISTICS
 

CONTACT RETENTION: 50gf/pin Min
- ELECTRICAL CHARACTERISTICS
 

RATING CURRENT: 1A  
 RATING VOLTAGE: 12V  
 CONTACT RESISTANCE: 100 MILLOHMS OHMS MAX  
 INSULATION RESISTANCE:  
 a, UNMATED: 1000M OHMS MIN  
 b, MATED: 100M OHMS MIN  
 DIELECTRIC WITHSTANDING VOLTAGE:  
 500V AC/1MINUTE  
 OPERATING TEMPERATURE: -25°C---+70°C  
 STORAGE TEMPERATURE: -10°C---+40°C

5. PART NO.

C-S3 06 150 A1-1  
 C: CARD TYPE      1: GOLD PLATED G/F  
 S3: MICRO SIM CARD      A1: SERIAL NUMBER  
 06: 6Pin      150: 1.50mm HEIGHT

GENERAL TOLERANCE		DWG NO.	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5°	Title	CHKD:		UNIT	mm
.X±0.35	.x'±2°		DR:			
.XX±0.25	.xx'±1°	Part NO.	Date	2017/10/17		
.XXX±0.15	.xxx'±0.5°					
SHEET	1/1	东莞市铭标电子科技有限公司 Ming Biao Electronic Technology Co., Ltd.				